

**Amendments to the Specification:**

Please replace the paragraph, beginning at page 7, line 17, with the following rewritten paragraph:

The method for inhibiting the precipitation of the metal intended to constitute the plating layer on the cathode rolls causing such problems is not yet found. At present, after the apparatus has been operated for a certain time, the production is ~~seopped~~ stopped, and the metal precipitated and deposited on the cathode rolls is scraped off. Then, the operation of the apparatus is resumed. The metal removal from the cathode rolls remarkably lowers the productivity of the plated film.

Please replace the paragraph, beginning at page 10, line 17, with the following rewritten paragraph:

Electric and electronic apparatuses are being substituted by IC version, and become more highly dense and more highly integrated at a rapid pace. In this connection, the wire pitch of patterns of flexible printed circuit boards become finer from a pitch ranging from 150 to 200  $\mu\text{m}$  to a pitch ranging from 80 to 150  $\mu\text{m}$ , and presently there is a demand for producing ~~patters~~ patterns at a wire pitch ranging from 30 to 80  $\mu\text{m}$ . In future, a demand for producing patterns at a wire pitch of less than 80  $\mu\text{m}$  is expected to arise.

Please replace the paragraph, beginning at page 33, line 21, with the following rewritten paragraph:

As the base film used for producing the plated film, a film formed of a polyimide resin or polyester resin can be preferably used. In ~~he~~ the case where a copper-plated film as used for electronic circuit materials is formed, a general purpose polyester resin film can be preferably used as the base film. In the case where solder heat resistance is required for mounting circuit ICs or the like, a polyimide resin film can be preferably used as the base film.